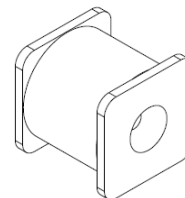


Gas Discharge Tube

Features

- Size Design 7.0×6.0×6.0mm
- High Current Handling Capability 10,000A @ 8/20μs
- Low Capacitance and Insertion Loss
- Fast Response and Long Service Life
- Reliable to Protect Electrostatic Surge
- Moisture sensitivity level: Level 1

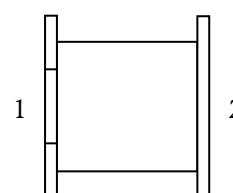
Exterior



Application Information

- Coaxial Port

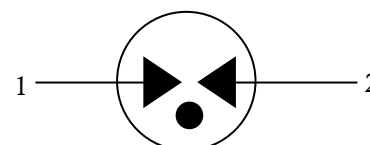
Package (Top View)



Agency Approvals

Icon	Description
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free
	Compliance with UL497B, Certificated E232249

Schematic Symbol



Electrical Parameter

DC Breakdown Voltage ^{1) 2)}	100V/s	150±20%	V
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ≤ 700	V
	At 1kV/μs	Typical values of distribution ≤ 650	V
Impulse Discharge Current ³⁾	8/20μs ±5times	10,000	A
Arc Voltage	At 1A	~12	V
Insulation Resistance	DC=100V	≥1	GΩ
Capacitance at 1MHz ⁴⁾	V _{DC} =0.5V	≤0.45	pF
Weight		~0.8	g
Operating and storage Temperature		-40-90	°C
Marking		Without	

1) At delivery AQL 0.65 level II ISO 2859

2) In ionized mode

3) Terms and current waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

4) Tested by Tonghui LCR meter

Part Numbering System

BW XXX M
(1) (2) (3)

(1)Bencent SMD Gas Discharge Tube in 7×6×6 (L×W×H) (mm)

(2) DC Breakdown Voltage, e.g., 151=15×10¹=150V

(3) Tolerance is DC Breakdown Voltage, M=±20%, N=±30%

Product Characteristics

Lead Material	Copper
Body Material	Ceramics
Terminal Finish	100% Matte-Tin Plated

Environmental Reliability Characteristics

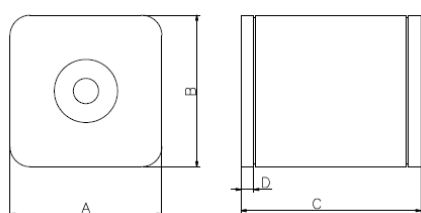
Testing items	Technical standards
High Temperature Storage Test	Temperature: 90℃ Time:2H
Low Temperature Storage Test	Temperature: -40℃ Time:2H
Vibration	Frequency: 10-500Hz Amplitude: 0.15mm Time: 45min
Resistance of soldering heat	Temperature: 260±5℃ Time of dip soldering: 10s, 1times

Note: Up-screen program can be specified by customer's request via contacting Bencent service

Solderability Test

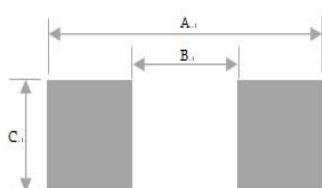
Solderability	Solder Pot Temperature:	245℃±5℃	Lead-Free Recommendation
	Solder Dwell Time:	4-6 seconds	

Product Dimensions



REF	Mm	inch
A	6±0.5	0.236±0.02
B	6±0.5	0.236±0.02
C	7±0.5	0.276±0.02
D	0.5±0.1	0.197±0.004

Recommended Soldering Pad

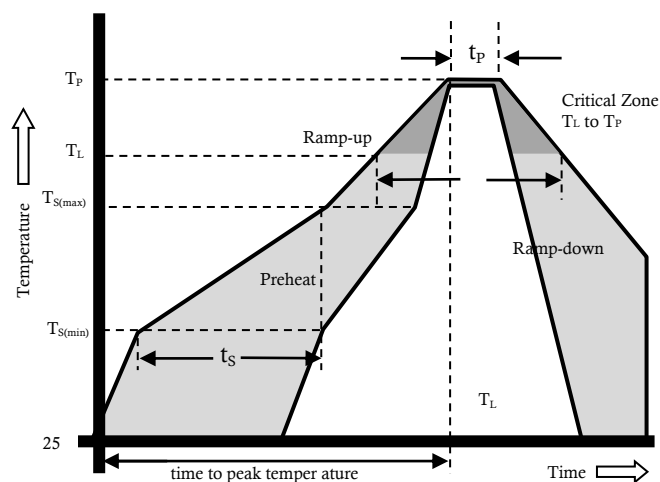


REF	Mm	inch
A	9	0.354
B	5	0.197
C	6.6	0.260

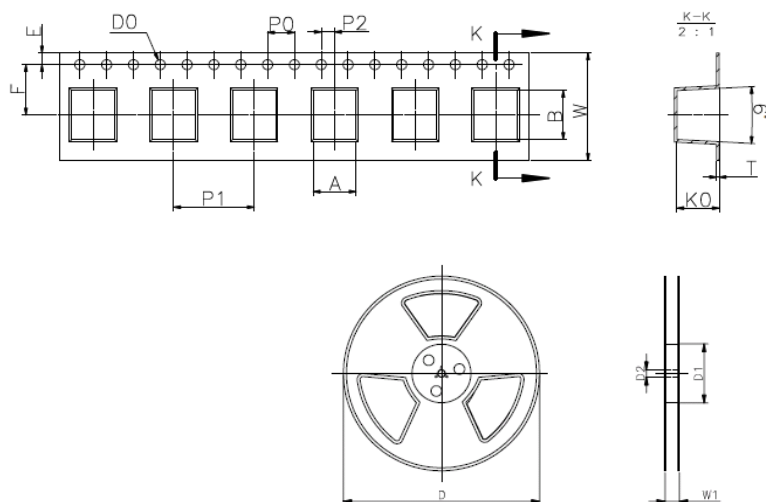
Gas Discharge Tube

Reflow Profile

Reflow Condition		Pb-Free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time (min to max)	60 – 180 secs
Average ramp up rate (Liquids) Tamp (T _L) to peal		3°C/second max
T _S (max) to T _L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T _L) (Liquids)	217°C
	- Temperature (T _L)	60 – 150 seconds
Peak Temperature (T _p)		260+0/-5 °C
Time within 5°C of actual peak Temperature (t _p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T _p)		8 minutes Max.
Do not exceed		260°C



Package Reel Information



REF	mm	inch
A	6.4±0.2	0.252±0.008
B	7.3±0.2	0.287±0.008
D0	1.5±0.2	0.059±0.008
E	1.75±0.2	0.069±0.008
F	7.5±0.2	0.295±0.008
P0	4±0.2	0.157±0.008
P1	12±0.5	0.472±0.020
P2	2±0.2	0.079±0.008
W	16±0.5	0.630±0.020
K0	6.3±0.2	0.248±0.008
T	0.4±0.05	0.016±0.002
D	Φ330±2	Φ12.99±0.079
D1	Φ100 ⁺¹ ₋₂	Φ3.94 ^{+0.039} _{-0.078}
D2	Φ13±0.15	0.512±0.006
W1	16.5±0.4	0.65±0.016

Package Box Information

Outline	Reel (PCS)	INSIDE CARTON (PCS)	Per Carton (PCS)	Carton Size(mm)		
				L	W	H
Box	800	1600	12800	360	360	380